

4

3

2

1

THIS DRAWING IS UNPUBLISHED.

RELEASED FOR PUBLICATION

2005

© COPYRIGHT 2005

BY TYCO ELECTRONICS CORPORATION. ALL RIGHTS RESERVED.

LOC

DIST

REVISIONS

J

-

P	LTR	DESCRIPTION	DATE	DWN	APVD
	A	RELEASED	17AUG2005	T.K	M.K
	B	REVISED	24DEC2008	T.K	M.K
	B1	REVISED	14JUL2009	S.N	M.K

108

100±0.15

(92.1)

30.2

35.1

26±0.15

5.6

Ø 3.2

4PLC

1

5

6

2

14.1

25

15.4

0.64

0.5

0.4

2.54x9=30.3

22.86

30.3

16.51

2.54x12=30.48

2.54x12=30.48

92.1

Ø 3

3

DATE CODE

xxxxx

SCALE 1:2

4

SCALE 1:2

SCALE 1:2

R3

Ø 3.5

6PLC

26±0.1

30.8MIN

92.6MIN

100±0.1

RECOMMENDED PANEL HOLE PATTERN

推奨パネル取り付け寸法

RoHS COMPLIANT

6

アダプタ スタビライザ

ADAPTOR STABILIZER

1

合成樹脂

PLASTIC

無し

NONE

UL94V-0

5

メタルプレート

METAL PLATE

1

ステンレス鋼

STAINLESS STEEL

無し

NONE

4

サポートハウジング

SUPPORT HOUSING

20

合成樹脂

PLASTIC

無し

NONE

UL94V-0

3

タッピングスクリュー

TAPPING SCREW L=8

2

鋼

STEEL

3価クロメート

TRIVALENT CHROMATE

2

コンタクト

0.64x0.4 CONTACT

(260)

ベリリウム銅

BERYLLIUM COPPER

ニッケル下地金メッキ

Au OVER Ni PL.

1

ハウジングリセアッシー

HOUSING RECE ASSY

1

ナイロン樹脂

NYLON RESIN

無し

NONE

UL94V-0

符号

名前

数量

材質

仕上

備考

ITEM

DESCRIPTION

QTY

MATERIAL

FINISH

REMARK

THIS DRAWING IS A CONTROLLED DOCUMENT FOR TYCO ELECTRONICS CORPORATION
IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION
SHOULD BE CONTACTED FOR THE LATEST REVISION.

DIMENSIONS:

mm

0-PLC

±

1-PLC

±

2-PLC

±

3-PLC

±

4-PLC

±

ANGLES

±3

TOLERANCES UNLESS
OTHERWISE SPECIFIED:

±0.3

MATERIAL

SEE TABLE

FINISH

SEE TABLE

DWN

T.KANNO

17AUG2005

CHK

E.TAKEMASA

17AUG2005

APVD

M.KIMURA

17AUG2005

PRODUCT SPEC

108-5483

APPLICATION SPEC

-

WEIGHT

112g

CUSTOMER DRAWING

Tyco Electronics

Tyco Electronics Corporation

Kawasaki, Japan

NAME

M-ZIF CONN RECE 260P

LONG SOLDER TYPE

SIZE

CAGE CODE

DRAWING NO

RESTRICTED TO

A3

00779

©=5316600

-

SCALE

1:1

SHEET

1

OF

1

REV

B1

1. PLATING: MATING AREA: 1.27µm MIN GOLD OVER 1.27~2.54µm NICKEL
SOLDER LEG AREA: GOLD FLASH OVER 1.27~2.54µm NICKEL
OTHERS: 1.27µm~2.54µm NICKEL

1. めっき: 接触部: ニッケル下地 1.27~2.54µm の上に金 1.27µm MIN
半田付け部: ニッケル下地 1.27~2.54µm の上に金フラッシュ
その他: ニッケル 1.27µm~2.54µm

AMP 1470-19 REV 31MAR2000